

### Law Offices

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### FACSIMILE TRANSMISSION COVER SHEET

DATE:

February 25, 2002

TO:

Examiner Jack Chen

Group Art Unit: 2813

RE:

Preliminary Amendment

U.S. Patent Appln. S.N. 09/321,605

By: SASHIDA et al.

Our Reference: P3329-698-A990535

FROM:

Thomas E. Brown

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FEB 25 2002

TECHNOLOGY CENTER 2800

NUMBER OF PAGES (INCLUDING THIS COVER SHEET): 12

### Dear Examiner Chen:

As requested by you earlier today on the telephone, attached is a copy of the Preliminary Amendment filed February 15, 2002.

## PLEASE ACKNOWLEDGE SAFE AND CLEAR RECEIPT OF ALL PAGES BEING SENT

TEB/kas 7/2

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FROM ARMSTRONG, WESTERMAN-

(MÓN) - 2. 25' 02 13:43/ST-13:42/NO. 486

# IN THE UNITED STATES PATENT AND TRADEMARK OFFICE AX COP

In re the Application of:

SASHIDA et al.

Serial Number: 09/321,605

Filed: May 28, 1999

Group Art Unit: 2813

Examiner: J. Chen

For: METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE HAVING CAPACITOR

### PRELIMINARY AMENDMENT

Commissioner for Patents Washington, D.C. 20231

February 15, 2002

Sir:

Prior to examination on the merits, please amend the above-identified application as follows:

### IN THE CLAIMS:

Please amend claims 1 and 21 as follows:

(Thrice Amended) 1.

A method of manufacturing a semiconductor device comprising

the steps of:

forming a couple of impurity diffusion layers in a semiconductor substrate;

forming a first insulating film covering the semiconductor substrate;

forming a lower electrode of a capacitor on the first insulating film;

forming an oxide dielectric film of the capacitor on the lower electrode;